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2013年12月

FGA60N65SMD 650 V, 60 A 场截止 IGBT

特性

- 最大结温: T_J = 175°C • 正温度系数,易于并联运行
- 高电流能力
- 低饱和电压: V_{CE(sat)} = 1.9 V (Typ.) @ I_C = 60 A
- 快速开关: E_{OFF} = 7.5 μJ/A
- 紧密的参数分布
- 符合 RoHS 标准

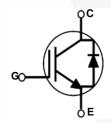
应用

• 光伏逆变器、UPS、焊机、PFC、通信电源、ESS

概述

飞兆半导体的新型场截止第二代 IGBT 系列产品采用创新型场截 止 IGBT 技术,为光伏逆变器、UPS、焊机、通信电源、ESS 和PFC 等低导通和开关损耗至关重要的应用提供最佳性能。





绝对最大额定值

符号	说明		额定值	单位
V _{CES}	集电极一发射极间电压		650	V
V _{GES}	栅极一发射极间电压		± 20	V
GES	瞬态栅极一发射极间电压		± 30	V
Ic	集电极电流	@ T _C = 25°C	120	A
	集电极电流	@ T _C = 100°C	60	A
I _{CM (1)}	集电极脉冲电流		180	A
IF	二极管正向电流	@ T _C = 25°C	60	A
'F	二极管正向电流	@ T _C = 100°C	30	Α
I _{FM (1)}	二极管最大正向脉冲电流		180	А
P _D	最大功耗	@ T _C = 25°C	600	W
. р	最大功耗	@ T _C = 100°C	300	W
T _J	工作结温		-55 至 +175	°C
T _{stg}	存储温度范围		-55 至 +175	°C
T _L	用于焊接的最大引脚温度,距离外	売 1/8",持续 5 秒	300	°C

注意: 1: 重复额定值:脉宽受最大结温限制

热性能

符号	参数	典型值	最大值	单位
$R_{\theta JC}(IGBT)$	结点-壳体的热阻		0.25	°C/W
$R_{\theta JC}(Diode)$	结点一壳体的热阻		1.1	°C/W
$R_{\theta JA}$	结至环境热阻		40	°C/W

封装标识与定购信息

器件标识	器件	封装	卷尺寸	带宽	数量
FGA60N65SMD	FGA60N65SMD	TO-3PN			30

IGBT 电气特性 TC = 25℃ 除非另有说明

符号	参数	测试条件	最小值	典型值	最大值	单位
关断特性						
BV _{CES}	集电极一发射极击穿电压	$V_{GE} = 0 \text{ V}, I_{C} = 250 \mu\text{A}$	650			V
$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	击穿温度系数电压	$V_{GE} = 0 \text{ V, } I_{C} = 250 \mu\text{A}$		0.6		V/°C
I _{CES}	集电极切断电流	V _{CE} = V _{CES} , V _{GE} = 0 V			250	μΑ
I _{GES}	G-E 漏电流	$V_{GE} = V_{GES}, V_{CE} = 0 V$			±400	nA
导通特性						
V _{GE(th)}	G-E 阈值电压	$I_C = 250 \mu A, V_{CE} = V_{GE}$	3.5	4.5	6.0	V
. ,		I _C = 60 A, V _{GE} = 15 V		1.9	2.5	V
V _{CE(sat)}	集电极一发射极间饱和电压	$I_C = 60 \text{ A}, V_{GE} = 15 \text{ V},$ $T_C = 175^{\circ}\text{C}$		2.1		V
动态特性						
C _{ies}	输入电容			2915		pF
C _{oes}	输出电容	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz		270		pF
C _{res}	反向传输电容	1 - 1 101112		85		pF
开关特性						
t _{d(on)}	导通延迟时间			18	27	ns
t _r	上升时间			47	70	ns
t _{d(off)}	关断延迟时间	$V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A},$		104	146	ns
t _f	下降时间	$R_G = 3 \text{ W}, V_{GE} = 15 \text{ V},$		50	68	ns
E _{on}	导通开关损耗	————感性负载, T _C = 25 °C		1.54	2.31	mJ
E _{off}	关断开关损耗			0.45	0.60	mJ
E _{ts}	总开关损耗			1.99	2.91	mJ
t _{d(on)}	导通延迟时间			18		ns
t _r	上升时间			41		ns
t _{d(off)}	关断延迟时间	$V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A},$		115		ns
t _f	下降时间	$R_G = 3 \text{ W}, V_{GE} = 15 \text{ V},$		48		ns
E _{on}	导通开关损耗	───── 感性负载, T _C = 175 °C		2.08		mJ
E _{off}	关断开关损耗			0.78		mJ
E _{ts}	总开关损耗			2.86		mJ

IGBT 电气特性 (婁)

符号	参数	测试条件	最小值	典型值	最大值	单位
Q_g	总栅极电荷			189	284	nC
Q _{ge}	栅极一发射极间电荷	$V_{CE} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $V_{GE} = 15 \text{ V}$		20	30	nC
Q _{gc}	栅极一集电极间电荷	VGE - 10 V		91	137	nC

二极管电气特性 Tc = 25°C 除非另有说明

符号	参数	测试条件	‡	最小值	典型值	最大值	单位
V _{FM}	二极管正向电压	I _E = 30 A	$T_C = 25^{\circ}C$		2.1	2.6	V
FIVI			$T_C = 175^{\circ}C$		1.7		
E _{rec}	反向恢复电能		$T_C = 175^{\circ}C$		127		uJ
t	t _{rr} 二极管反向恢复时间	Ι_ =30 Δ	$T_C = 25^{\circ}C$		47		ns
TI		$I_F = 30 \text{ A},$ $dI_F/dt = 200 \text{ A}/\mu\text{s}$	$T_C = 175^{\circ}C$		212		
Q _{rr}	二极管反向恢复电荷		$T_C = 25^{\circ}C$		87		nC
			$T_C = 175^{\circ}C$		933		

图 1. 典型输出特性

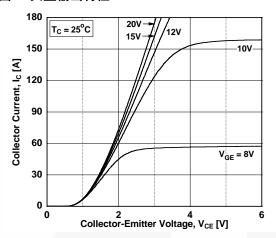


图 2. 典型输出特性

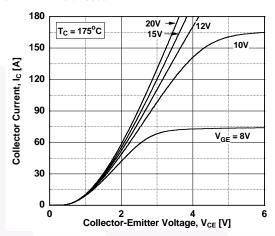


图 3. 典型饱和电压特性

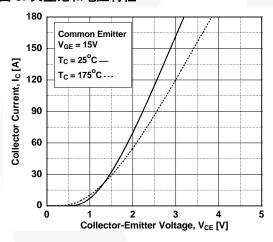


图 4. 典型饱和电压与可变电流强度下壳温的关系

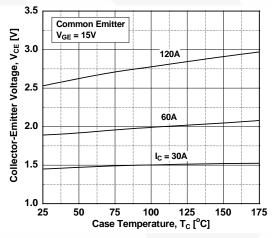


图 5. 饱和电压与 V_{GE} 的关系

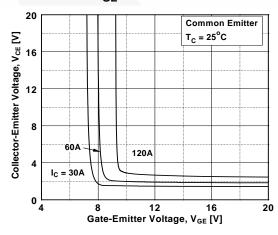


图 6. 饱和电压与 V_{GE} 的关系

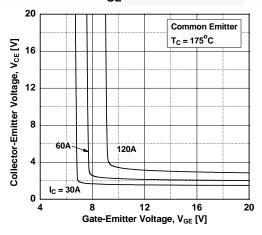


图 7. 电容特性

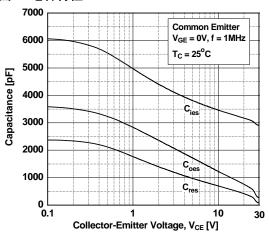


图 8. 栅极电荷特性

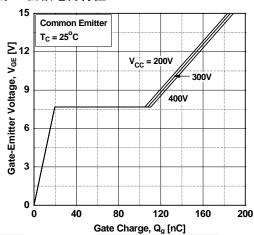


图 9. 导通特性与栅极电阻的关系

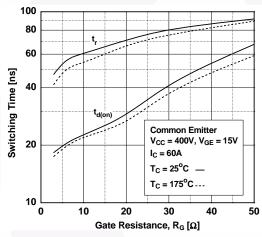


图 10. 关断特性与栅极电阻的关系

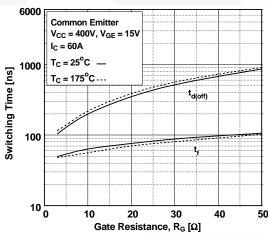


图 11. 开关损耗与栅极电阻的关系

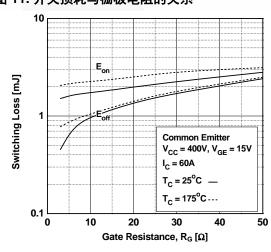


图 12. 导通特性与集电极电流的关系

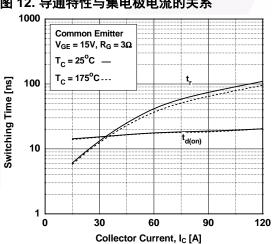


图 13. 关断特性与集电极电流的关系

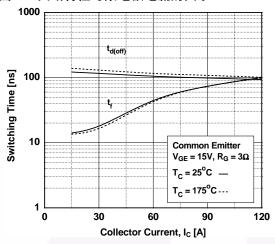


图 14. 开关损耗与集电极电流的关系

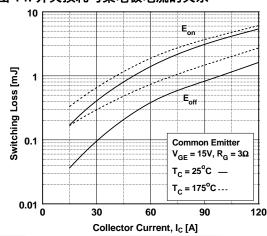


图 15. 负载电流与频率的关系

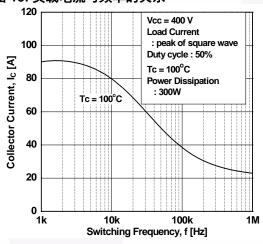


图 16. SOA 特性

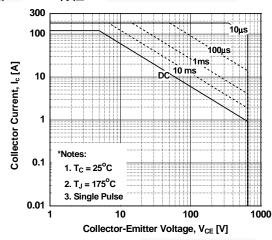


图 17. 正向特性

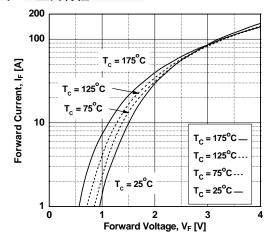


图 18. 反向恢复电流

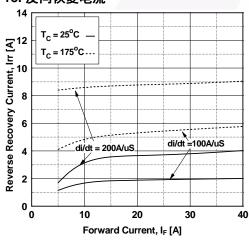


图 19. 反向恢复时间

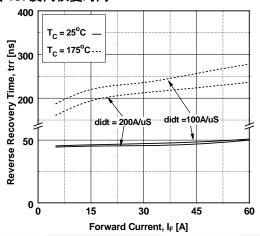


图 20. 存储电荷

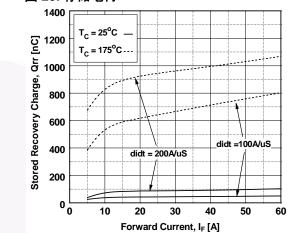


图 21. IGBT 的瞬态热阻

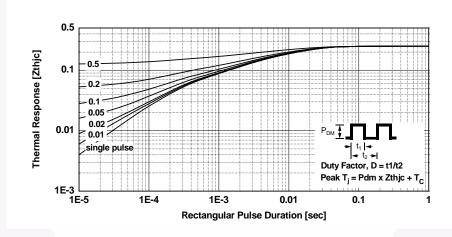
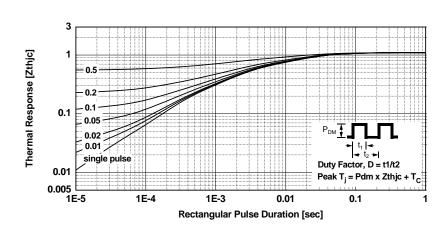
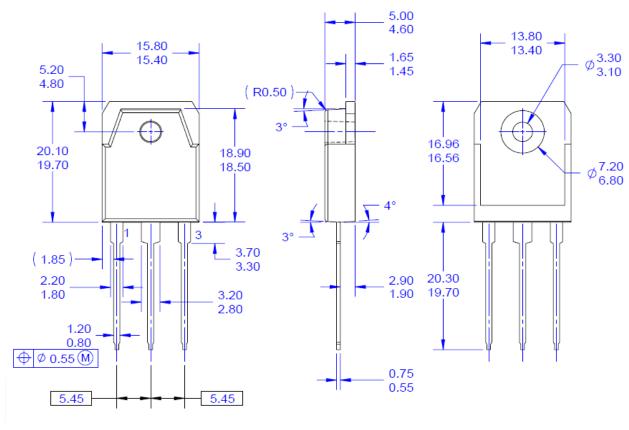


图 22. 二极管瞬态热阻抗



机械尺寸



(R0.50)

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- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS. MOLD FLASH, AND TIE BAR EXTRUSSIONS.
 E) THIS PACKAGE IS INTENDED ONLY FOR TO3PN.
- F) DRAWING FILE NAME: TO3P03AREV4.

图 20. TO-3P 3L - 3LD, T03, PLASTIC, EIAJ SC-65

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